Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			***: Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	01/14/2015
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	**Representative Title**	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EBE3*0393BF6	A	ZY1A	01/14/2015
	Amount	UoM	Unit type	ST ECOPACK Grade
	28.000	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY3.00 PITCH0.65; MD valid for LM2903YST			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th June 2014	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EBE3*0393BF6					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
SILICON DIE	Other inorganic materials	0.551	mg	supplier	Die	Silicon (Si)	7440-21-3		0.539	mg	978221	19250
SILICON DIE			mg	supplier	Metallization	Aluminium (Al)	7429-90-5		0.007	mg	12704	250
SILICON DIE			mg	supplier	Passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	3630	71
SILICON DIE			mg	supplier	Passivation	Silicon Oxide(SiO2)	7631-86-9		0.003	mg	5445	107
LEADFRAME	Copper and its alloy	13.542	mg	supplier	Alloy	Copper (Cu)	7440-50-8		12.828	mg	947275	458143
LEADFRAME			mg	supplier	Alloy	Nickel (Ni)	7440-02-0		0.399	mg	29464	14250
LEADFRAME			mg	supplier	Alloy	Silicon (Si)	7440-21-3		0.086	mg	6351	3071
LEADFRAME			mg	supplier	Alloy	Magnesium (Mg)	7439-95-4		0.02	mg	1477	714
LEADFRAME			mg	supplier	Coating	Nickel (Ni)	7440-02-0		0.203	mg	14990	7250
LEADFRAME			mg	supplier	Coating	Palladium (Pd)	7440-05-3		0.004	mg	295	143
LEADFRAME			mg	supplier	Coating	Gold (Au)	7440-57-5		0.002	mg	148	71
DIE ATTACH	Other organic materials	0.298	mg	supplier	Glue	Epoxy resin A	9003-36-5		0.021	mg	70470	750
DIE ATTACH			mg	supplier	Glue	Epoxy resin B	68475-94-5		0.012	mg	40268	429
DIE ATTACH			mg	supplier	Glue	Silver(Ag)	7440-22-4		0.229	mg	768456	8179
DIE ATTACH			mg	supplier	Glue	Lactone	96-48-0		0.012	mg	40268	429
DIE ATTACH			mg	supplier	Glue	Polyoxypropylenediamine	9046-10-0		0.012	mg	40268	429
DIE ATTACH			mg	supplier	Glue	2,6-Diglycidyl phenyl allyl ether oligomer	EC 417-470-1		0.012	mg	40268	429
BONDING WIRE	Other inorganic materials	0.078	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.078	mg	1000000	2786
ENCAPSULATION	Other inorganic materials	13.531	mg	supplier	Molding compound	Epoxy Resin	Proprietary		1.213	mg	89646	43321
ENCAPSULATION			mg	supplier	Molding compound	Silica fused (SiO2)	60676-86-0		11.324	mg	836893	404429
ENCAPSULATION			mg	supplier	Molding compound	Phenol Resin	Proprietary		0.876	mg	64740	31286
ENCAPSULATION			mg	supplier	Molding compound	Carbon Black	1333-86-4		0.067	mg	4952	2393
ENCAPSULATION			mg	supplier	Molding compound	Bismuth (Bi)	7440-69-9		0.051	mg	3769	1821